

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A thermal device for applying thermal energy to the body of a person, animal or other surface, comprising:
 2. degermed corn grain; and
 4. an enclosure configured to enclose said degermed corn grain.
2. (original) The thermal device of Claim 1, wherein said enclosure is made from fabric.
2. 3. (currently amended) The thermal device of Claim 1, wherein said degermed corn grain is kiln dried.
2. 4. (currently amended) The thermal device of Claim 1, wherein said degermed corn grain is oven dried.
2. 5. (original) The thermal device of Claim 1, wherein said enclosure is generally rectangular.
2. 6. (currently amended) A thermal device for applying thermal energy to the body of a person, animal or other surface, comprising segmented-degermed grain configured to accept thermal energy.

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Reply to Office action of Dec. 10, 2004

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7. (currently amended) A method of applying thermal energy to the body of a person, animal or other surface, comprising:

providing a thermal device including segmented degemed grain;

subjecting said thermal device to thermal energy; and

applying said thermal device to a surface to be treated.

8. (currently amended) The thermal device of Claim 7, wherein said segmented degemed grain is corn.

9. (cancelled)

10. (currently amended) The thermal device of Claim 7, wherein said segmented degemed grain is embryo-free corn.

11. (currently amended) The thermal device of Claim 10, wherein said degermed embryo-free corn dissipates thermal energy relatively slowly.

12. (currently amended) A thermal device for applying thermal energy to the body of a person, animal or other surface, comprising:

segmented degemed organic filler; and

4 a receptacle configured to enclose said segmented-degermed organic
filler.

13. (currently amended) The thermal aid of Claim 12, wherein said segmented-degermed
2 organic filler is degermed grain.

14. (currently amended) The thermal aid of Claim 12, wherein said segmented-degermed
2 organic filler is embryo-free grain.

15. (currently amended) The thermal aid of Claim 12, wherein said segmented-degermed
2 organic filler is kiln-dried grain.

16. (currently amended) The thermal device of Claim 12, wherein said segmented
2 degermed organic filler is oven dried.

17. (currently amended) The thermal aid of Claim 12, wherein said segmented-degermed
2 organic filler is dissected grain.

18. (currently amended) The thermal aid of Claim 12, wherein said segmented-degermed
2 organic filler is corn.

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19. (original) The thermal device of Claim 12, wherein receptacle is generally
2 rectangular.

20. (currently amended) A method of making a thermal device, comprising:

2 providing grain;
segmenting said grain to provide degerned grain; and
4 enclosing said segmented degermed grain in an enclosure.

21. (original) The method of Claim 20, wherein said segmenting comprises:

2 cleaning the grain to remove foreign material;
tempering the grain;
4 removing the embryo;
sifting out undesirable elements to produce a resulting grain; and
6 drying said resulting grain.

22. (new) The thermal device of Claim 1, wherein said degerned grain is corn.